

	Type	Hit s	Search Text	DBs	Time Stamp	Cor ro mm en ts	De en ni ti on	Er ro rs	Ref #
1	IS&R	2	("6642158") .PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/30 12:22				S1
2	IS&R	3	("5821627") .PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 22:25				S2
3	IS&R	2	("6486553") .PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 22:26				S3
4	IS&R	2	("4376154") .PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 22:26				S4
5	IS&R	2	("4983250") .PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 22:27				S5
6	IS&R	2	("5230965") .PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 22:27				S6
7	IS&R	2	("5264108") .PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 22:28				S7
8	IS&R	2	("4457950") .PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 22:28				S8

	Type	Hit s	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro r Er ro rs	Ref #
9	IS&R	2	("4925522").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 22:29				S9
10	BRS	3	"2003102262"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 22:33				S10
11	BRS	3	"2002063394"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 22:35				S11
12	BRS	3	"2000021546"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/27 22:37				S12
13	BRS	1	2002-636602.NRAN.	DERWENT	2004/11/29 10:23				S13
14	BRS	45	(tin or sn) near (copper or cu) near alloy with substrate	DERWENT	2004/11/30 16:13				S14
15	BRS	1	(tin or sn) near (copper or cu) near alloy with substrate and (package or pcb or circuit adj board or die) and (tin or sn) with organic	DERWENT	2004/11/27 23:00				S16

	Type	Hit s	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De ni ti on	Er ro r rs	Ref #
16	BRS	8	(tin or sn) near (copper or cu) near alloy with substrate and (package or pcb or circuit adj board or die)	DERWENT	2004/11/27 22:54				S15
17	BRS	10	(tin or sn) with precursor and alloy and (cu or copper)	DERWENT	2004/11/27 23:02				S18
18	BRS	31	"102262"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/29 10:24				S19
19	BRS	3	"2003102262"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/29 10:26				S20
20	BRS	1	2004-053486.NRAN.	DERWENT	2004/11/29 10:26				S21
21	BRS	3	"2003102262"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/29 10:26				S22
22	IS&R	3	("5821627").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/30 14:59				S23

			Search Text	DBs	Time Stamp	Cor ro mm en ts	De fi ni ti on	Er ro rs	Ref #
Type	Hit s								
23	BRS	5	apparatus and (tin or sn) near (copper or cu) near alloy with substrate	DERWENT	2004/11/30 16:13				S24
24	BRS	1	apparatus and (tin or sn) with precursor and alloy	DERWENT	2004/11/30 16:16				S25
25	BRS	62	apparatus with (tin or sn) with (cu or copper) with alloy	DERWENT	2004/11/30 16:17				S28